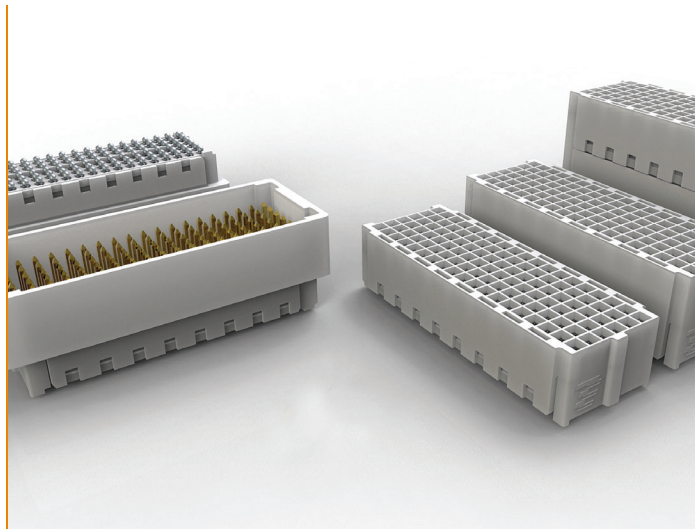


INTRODUCING

MEZALOK HIGH-SPEED LOW-FORCE XMC CONNECTOR

- **Faster speed (32+ Gb/s) and lower force**
- **Intermateable with legacy Mezalok pin connectors allowing ease of upgrade**



TE Connectivity's (TE) Mezalok High-Speed Low-Force (HSLF) XMC connectors are designed for mezzanine applications for rugged embedded computing interconnects. The connectors utilize a rugged dual point contact system that meets the qualification requirements of legacy Mezalok high speed connectors.

The connectors are available in 60, 114, and 320 positions with stack height options of 10, 12, 17 and 18 mm.

Mezalok High-Speed Low-Force XMC connectors meet the same rugged standards as listed in VITA 47 and VITA 72. The 114-position connector is compliant to VITA 61 and additional positions and stack heights are available. These High-Speed Low-Force connectors feature a wide operating temperature range, excellent thermal stability, and data rates to 32+ Gb/s, with VITA 42.3 pinout.

Mezalok high-speed low-force connectors utilize the reliable ball grid array printed circuit board surface mount application.

APPLICATIONS

- Embedded computing

TARGET MARKETS

- Aircraft
- Ground Vehicles
- Sea
- Space
- Missile Defense

KEY BENEFITS

- Unmating force reduction: 47% / Mating force reduction: 32%
- Rugged dual point contact system
- Maintains ball grid array (BGA) PCB attachment, supports standard surface mount processing
- Designed for highly rugged performance rating—meeting legacy Mezalok specification
- Testing to VITA 72 working group environment
- Thermal stability for reliable solder joints
- Multiple positions and stack heights available

STANDARDS & SPECIFICATIONS

- Product Specification: 108-2411
- Application Specification: 114-13279
- Qualification Test Report: 501-736
- HSLF Qualification Test Report: 501-134111
- Electrical Performance Report: 505-4
- White Paper: Mezalok White Paper

LEARN MORE

[Mezalok HSLF Connector product brochure](#)

[Mezalok HSLF part list](#)